

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



September 2015

FDS89141

Dual N-Channel Shielded Gate PowerTrench® MOSFET 100 V, 3.5 A, 62 m Ω

Features

- Shielded Gate MOSFET Technology
- Max $r_{DS(on)}$ = 62 m Ω at V_{GS} = 10 V, I_D = 3.5 A
- Max $r_{DS(on)} = 100 \text{ m}\Omega$ at $V_{GS} = 6 \text{ V}$, $I_D = 2.8 \text{ A}$
- High performance trench technology for extremely low r_{DS(on)}
- High power and current handling capability in a widely used surface mount package
- 100% UIL Tested
- RoHS Compliant

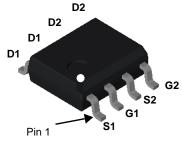


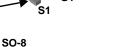
General Description

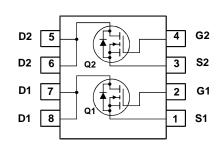
This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for $r_{DS(on)}$, switching performance and ruggedness.

Applications

- Synchronous Rectifier
- Primary Switch For Bridge Topology







MOSFET Maximum Ratings TA = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
V_{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous			3.5	۸
ID	-Pulsed			18	— A
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	37	mJ
D	Power Dissipation	T _A = 25 °C	(Note 1a)	31	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1b)	1.6	VV
T _J , T _{STG}	Operating and Storage Junction Temporation	erature Range		-55 to +150	°C

Thermal Characteristics

F	R _{eJC}	Thermal Resistance, Junction to Case	(Note 1)	40	°C/W
F	$R_{ heta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	78	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS89141	FDS89141	SO-8	13 "	12 mm	2500 units

Electrical Characteristics T_J = 25°C unless otherwise noted

Symbol	Parameter Test Conditions		Min	Тур	Max	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		69		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2	3.1	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25 °C		-9		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 3.5 \text{ A}$		47	62	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 6 \text{ V}, I_D = 2.8 \text{ A}$		63	100	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 3.5 \text{ A}, T_J = 125 \text{ °C}$		81	107	1
9 _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_D = 3.5 \text{ A}$		14.7		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 50 V, V _{GS} = 0 V, f = 1MHz	299	398	pF
C _{oss}	Output Capacitance		70	93	pF
C _{rss}	Reverse Transfer Capacitance		4.7	7	pF
R_g	Gate Resistance		1.0		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time				5	10	ns
t _r	Rise Time	V _{DD} = 50 V, I _D = 3.	$V_{DD} = 50 \text{ V}, I_{D} = 3.5 \text{ A},$		1.4	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, R _{GEN}	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		9.8	20	ns
t _f	Fall Time				2.2	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V _{GS} = 0 V to 10 V			5.1	7.1	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 V to 5 V$	$V_{DD} = 50 \text{ V},$		2.9	4.1	nC
Q _{gs}	Gate to Source Charge		$I_D = 3.5 \text{ A}$		1.4		nC
Q _{gd}	Gate to Drain "Miller" Charge				1.3		nC

Drain-Source Diode Characteristics

V _{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 3.5 \text{ A}$	(Note 2)	8.0	1.3	V
	Source to Drain Diode Polward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2 \text{ A}$	(Note 2)	8.0	1.2	\ \ \
t _{rr}	Reverse Recovery Time	-I _F = 3.5 A, di/dt = 100 A/μs		33	53	ns
Q _{rr}	Reverse Recovery Charge			23	37	nC

^{1.} R_{0JA} is determined with the device mounted on a 1in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a) 78°C/W when mounted on a 1 in² pad of 2 oz copper



b) 135°C/W when mounted on a minimun pad

^{2.} Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0%. 3. Starting T $_J$ = 25°C, L = 3.0 mH, I $_{AS}$ = 5.0 A, V $_{DD}$ = 100 V, V $_{GS}$ = 10V.

Typical Characteristics (N-Channel) T_J = 25°C unless otherwise noted

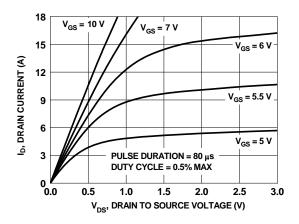


Figure 1. On-Region Characteristics

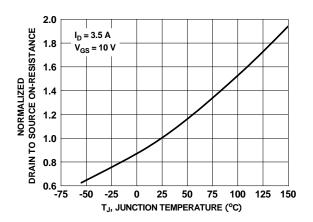


Figure 3. Normalized On-Resistance vs Junction Temperature

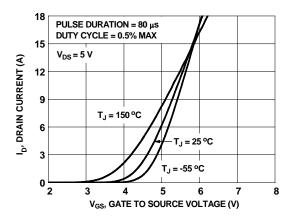


Figure 5. Transfer Characteristics

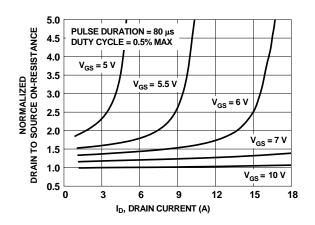


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

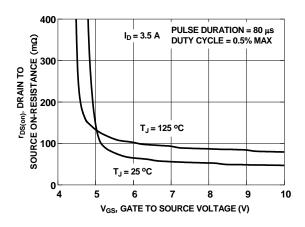


Figure 4. On-Resistance vs Gate to Source Voltage

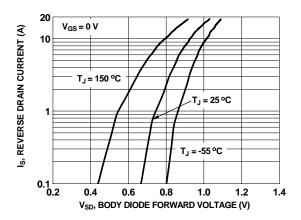


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics (N-Channel) T_J = 25°C unless otherwise noted

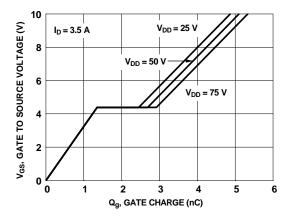


Figure 7. Gate Charge Characteristics

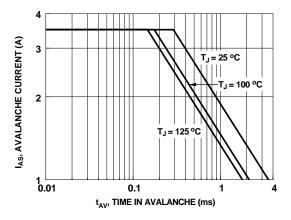


Figure 9. Unclamped Inductive Switching Capability

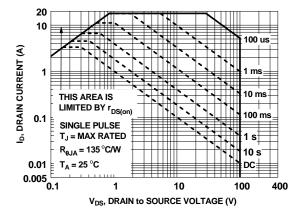


Figure 11. Forward Bias Safe Operating Area

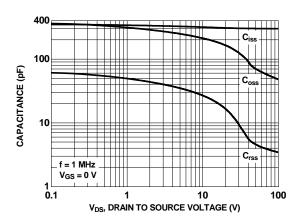


Figure 8. Capacitance vs Drain to Source Voltage

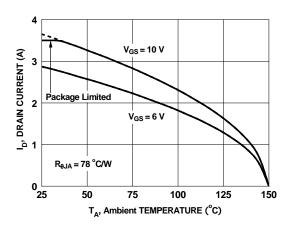


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

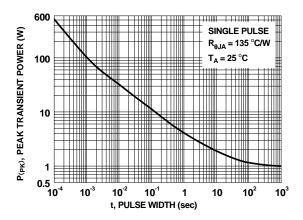


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics (N-Channel) T_J = 25°C unless otherwise noted

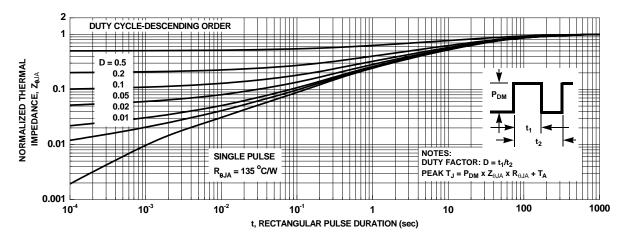
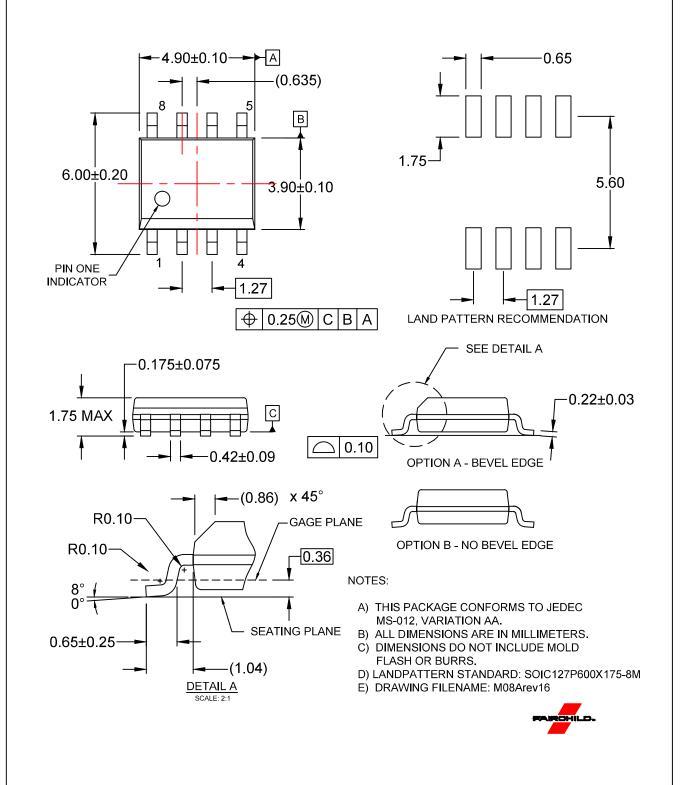


Figure 13. Junction-to-Ambient Transient Thermal Response Curve



ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by ON Semiconductor manufacturer:

Other Similar products are found below:

614233C 648584F IRFD120 JANTX2N5237 FCA20N60_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D TPCC8103,L1Q(CM MIC4420CM-TR VN1206L SBVS138LT1G 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C BUK954R8-60E NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE222 NTE2384 NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956 NTE2911 DMN2080UCB4-7 TK10A80W,S4X(S SSM6P69NU,LF DMP22D4UFO-7B